/ Descriptions

SOD-523

Silicon Diode in a SOD-523 Plastic Package.

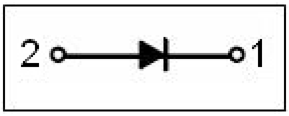
/ Features

Fast switching diodes,HF Product.

/ Applications

Small signal diode.

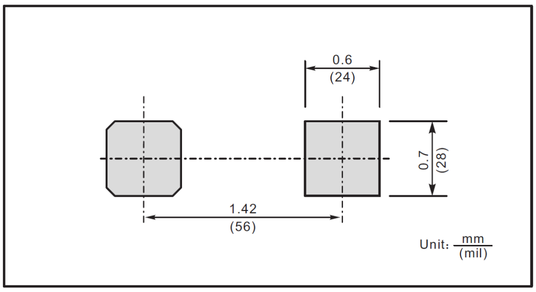
/ Equivalent Circuit



/ Pinning

PIN1:Cathode PIN2:Anode

The recommended mounting pad size



/ Marking

Marking	T4

Parameter	Symbol	Rating	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Continuous Forward Current	I_F	150	mA
Non-reptitive Peak Forward Surge Current	I_{FSM} t=1ms	0.8	A
Power Dissipation	P_{tot}	150	mW
Junction Temperature	T_j	-55 150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Breakdown Voltage	$V_{(BR)R}$	I_R=1 A	75			V
		I_F=1mA			0.715	V
[redacted]	[redacted]	[redacted]			0.855	

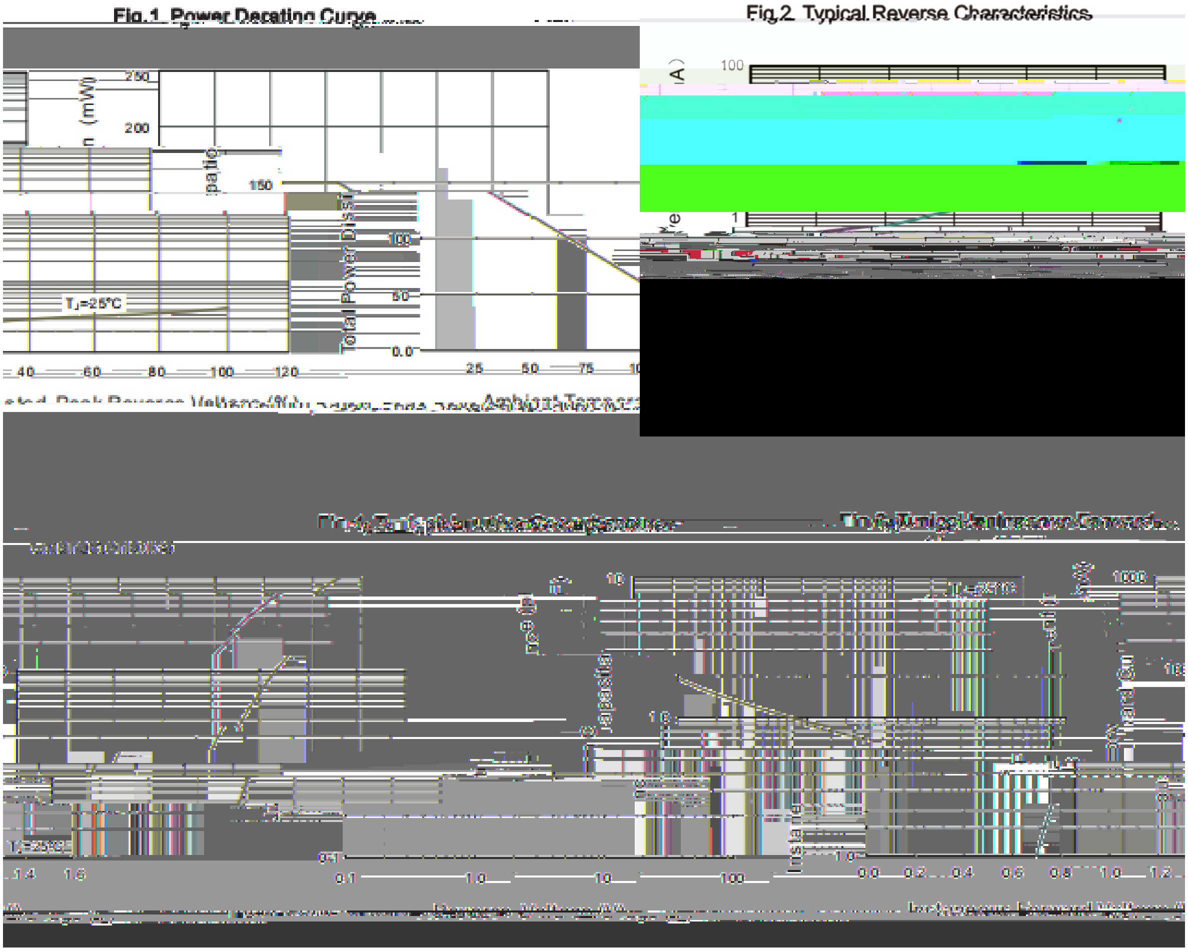
V V

[redacted]

[redacted]

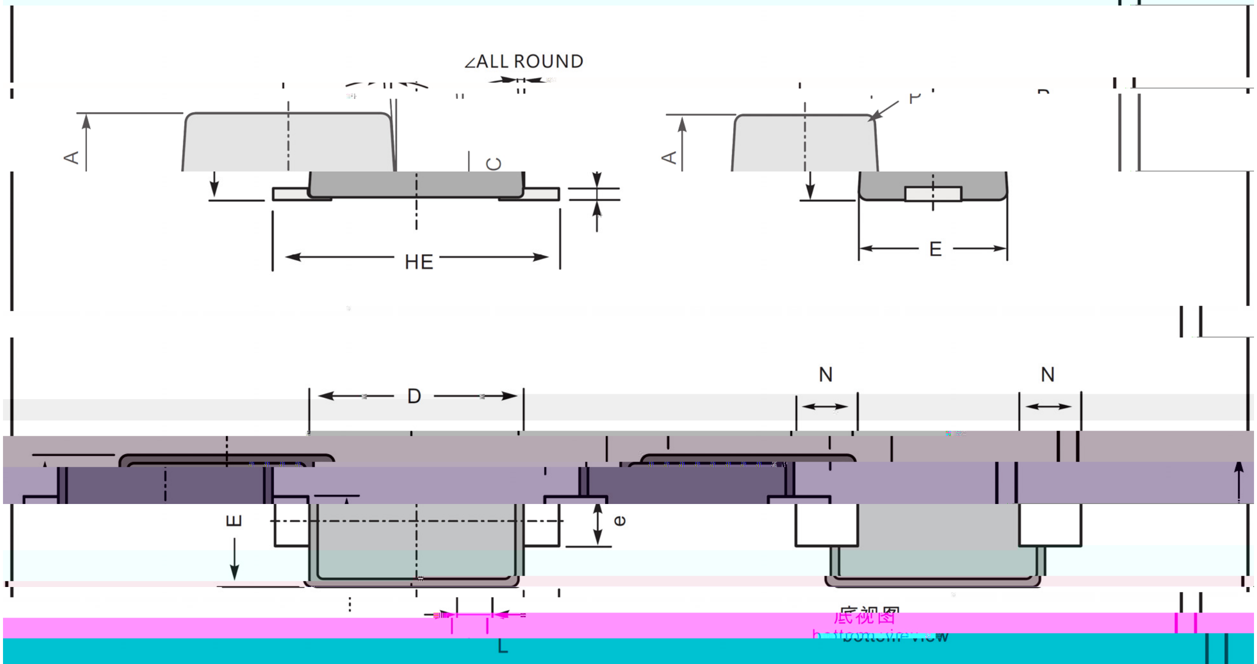
[redacted]

/ Electrical Characteristic Curve



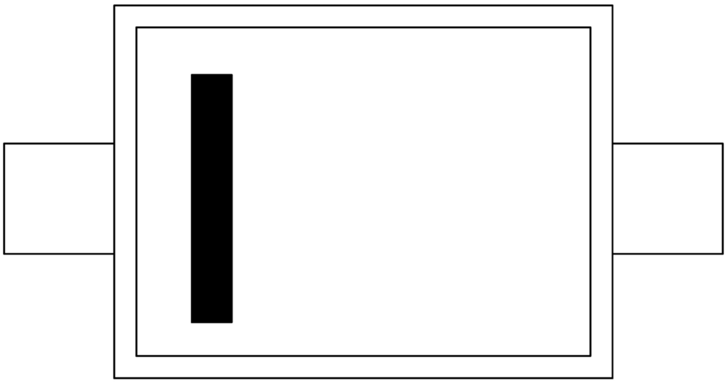
/ Package Dimensions

SOD-523



UNIT		A	e	C	D	E	HE	N	L	P
mm	max	0.77	0.35	0.15	1.30	0.99	1.70	0.35	0.2	R0.1
	min	0.51	0.25	0.08	1.10	0.75	1.50	ref.	ref.	ALL ROUND
mil	max	30	14	6	51	39	67	14	8.0	R4.0
	min	20	10	3	43	30	59	ref	ref	ALL ROUND

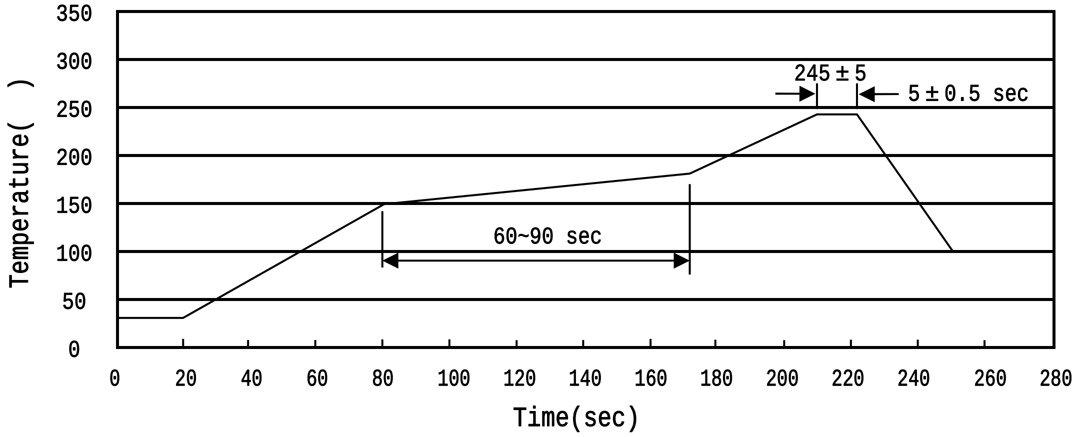
/ Marking Instructions



T4

T563.5ye

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 150 180 60 90sec;
2 245±5 5±0.5sec;
3 2 10 /sec.

1.Preheating:150~180 , Time:60~90sec.
2.Peak Temp.:245±5 , Duration:5±0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec.

Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOD-523	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices